

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Naoshi ADACHI et al.

Serial No.: 10/750,883

Filed: January 5, 2004



Art Unit: 2826

Examiner: Williams, Alexander

*Entered  
with  
RCE  
7/13/07*

For: HEAT TREATMENT JIG FOR SEMICONDUCTOR SUBSTRATE AND METHOD OF  
HEAT TREATING SEMICONDUCTOR SUBSTRATE

REQUEST FOR RECONSIDERATION

Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Final Office Action dated March 13, 2007 and the Advisory Action of June 28, 2007, Applicants request reconsideration of the final rejection of the claims in conjunction with the filing of this RCE.

The purpose of this Advisory Action is to address the comments made in the Advisory Action regarding the claim language and the failure to include the term "directly" in the claims.

The language in the Advisory Action implies that Applicants arguments in favor of patentability are not supported by the claims since the claims do not say "directly." However, the clause defining the first jig includes the language that the first jig "comes in direct contact with the semiconductor substrate... ."

Since a direct contact between the semiconductor substrate and the first jig is set forth in the claims, Applicants' argument that Minami does not teach a jig that directly contacts the semiconductor substrate is a legitimate argument that should be considered by the Examiner at this stage of the prosecution.

Moreover and as expressed in the 116 Amendment filed on June 13, 2007 (the "116 Amendment"), the presence of a requirement that the first jig comes in direct contact with the semiconductor substrate removes Minami as a reference under 35 U.S.C. § 102(b). The 116 Amendment is also relied upon herein to reiterate the arguments that Minami also does not set forth